



## Flexbase™ T900193 Electronic Materials Low-Flow Flame Retardant Unsupported Bonding Adhesive

### Description

Sheldahl Flexbase T900193 products use our proprietary low-flow, self-extinguishing adhesive on a release liner, creating an isolated adhesive suitable for use as bonding-layer. T900193 tapes are engineered for superior adhesion to copper, tin, and standard FFC/FPC materials. Sheldahl materials are able to be processed in rolls.

### Features

- **Adhesive:** Low-flow, flame-retardant.
- **Consistent:** Sheldahl's superior manufacturing process ensures consistent adhesive thickness control.
- **Processing:** T900193 is thermally activated and allows for efficient processing with no drying time.

### Storage

Material stored in original packaging, at temperatures of  $\leq 20^{\circ}\text{C}$  and  $\leq 50\%$  RH will retain their properties for a minimum of six months from date of shipment. Excessive exposure to heat and moisture may cause reduced shelf-life.

### Quality

Sheldahl products are manufactured using quality systems that conform to ISO, QS, and TS quality standards. Key product characteristics are tested and monitored in accordance to IPC standards. Certifications are available with product shipments.

### Constructions

- **Adhesive Thickness:** 1 – 2mil (25 – 50 $\mu\text{m}$ )
- **Width:** Standard roll width is 24" (610mm)

Specialty thickness and widths available please contact your Sheldahl representative.

### Contact Information:

USA: Telephone – 507-663-8344  
Europe: Telephone – 33-387-847-477  
Worldwide: Telephone – 507-663-8344

Come visit us at [www.Sheldahl.com](http://www.Sheldahl.com)

### Ordering Information:

When ordering please specify:

- Film thickness
- Adhesive type (flame-retardant or non flame-retardant)
- Adhesive thickness
- Adhesive on one side or both
- Roll width

PROPERTY TO BE TESTED AND TEST METHOD	Sheldahl Typical Mean Value*
Peel Strength, minimum, lb./in. - width, IPC-TM-650, Method 2.4.9 Method B as received	8.0
Flow, maximum IPC-TM-650, Method 2.3.17.1	1.5:1
Volatile Content, maximum IPC-TM-650, Method 2.3.37	1.5
Chemical Resistance percentage, IPC-TM-650, Method 2.3.2, A	90%
Fungus Resistance, IPC-TM-650, Method 2.6.1	Non-nutrient

\*The information contained herein is based upon typical data, Sheldahl makes no warranties expressed or implied as to its accuracy and assumes no liability arising out of its use by others. The user should determine suitability of Sheldahl materials for each individual application.

### Processing Recommendations

#### Roll-to-Roll Laminating

	SAE	Metric
Hot Roll Temperature	330 - 390°F	160 - 195°C
Pressure (minimum)	200 PSI	14 bar
Line Speed	12-20 FPM	2-8 M/min.
Exit Temperature	295°F (2.5 in. from nip point)	145°C (6cm from nip point)

#### Platen Press

Platen Temperature	275-300°F	135-160°C
Pressure	100-200 PSI	7-14 bar
Time (cool under pressure)	10 min to 120°F	10 min to 50°C

*\*Please note, actual values will depend on many factors including but not limited to: number of rollers, number of heated rollers, copper thickness and cable pitch, wrap angle of tape on heated rollers prior to lamination, run speed etc. Sheldahl suggests use of standard industry tests to confirm encapsulation and adhesion quality. Contact Sheldahl for assistance enhancing product performance.*